Freescale Semiconductor

MPX53 Rev 7, 05/2009

50 kPa Uncompensated Silicon Pressure Sensors

The MPX53 series silicon piezoresistive pressure sensors provide a very accurate and linear voltage output, directly proportional to the applied pressure. These standard, low cost, uncompensated sensors permit manufacturers to design and add their own external temperature compensating and signal conditioning networks. Compensation techniques are simplified because of the predictability of Freescale's single element strain gauge design.

Features

- Low Cost
- Patented Silicon Shear Stress Strain Gauge Design
- Ratiometric to Supply Voltage
- Easy to Use Chip Carrier Package Options
- 60 mV Span (Typical)
- · Differential and Gauge Options

MPX53 Series

0 to 50 kPa (0 to 7.25 psi) 60 mV Full Scale Span (Typical)

Application Examples

- Air Movement Control
- Environmental Control Systems
- · Level Indicators
- Leak Detection
- Medical Instrumentation
- · Industrial Controls
- · Pneumatic Control Systems
- Robotics

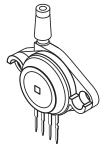
				ORDERIN	G INFORM	ATION			
Device Name	Package Case		# of Ports		Pressure Type		Device		
Device Mairie	Options	No.	None	Single	Dual	Gauge	Differential	Absolute	Marking
Unibody Packa	Unibody Package (MPX53 Series)								
MPX53D	Tape & Reel	344	•				•		MPX53D
MPX53DP	Rail	344C			•		•		MPX53DP
MPX53GP	Rail	344B		•		•			MPX53GP
Small Outline F	Small Outline Package (MPXV53G Series)								
MPXV53GC7U	Rail	482C		•		•			MPXV53G

SMALL OUTLINE PACKAGE

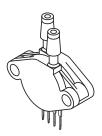
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MPX53D CASE 344-15

UNIBODY PACKAGES



MPX53GP CASE 344B-01



MPX53DP CASE 344C-01





Operating Characteristics

Table 1. Operating Characteristics ($V_S = 3.0 \text{ Vdc}$, $T_A = 25^{\circ}\text{C}$ unless otherwise noted, P1 > P2)

Characteristic	Symbol	Min	Тур	Max	Units
Pressure Range ⁽¹⁾	P _{OP}	0	_	50	kPa
Supply Voltage ⁽²⁾	V _S	_	3.0	6.0	V _{DC}
Supply Current	Io	_	6.0	_	mAdc
Full Scale Span ⁽³⁾	V _{FSS}	45	60	90	mV
Offset ⁽⁴⁾	V _{OFF}	0	20	35	mV
Sensitivity	ΔV/ΔΡ	_	1.2	_	mV/kPa
Linearity	_	-0.6	_	0.4	%V _{FSS}
Pressure Hysteresis (0 to 50 kPa)		_	±0.1	_	%V _{FSS}
Temperature Hysteresis		_	±0.5	_	%V _{FSS}
Temperature Coefficient of Full Scale Span	TCV _{FSS}	-0.22	_	-0.16	%V _{FSS} /°C
Temperature Coefficient of Offset	TCV _{OFF}	_	±15	_	μV/°C
Temperature Coefficient of Resistance	TCR	0.21	_	0.27	%Z _{IN} /°C
Input Impedance	Z _{IN}	355	_	505	Ω
Output Impedance	Z _{OUT}	750	_	1875	Ω
Response Time ⁽⁵⁾ (10% to 90%)	t _R	_	1.0	_	ms
Warm-Up Time ⁽⁶⁾		_	20	_	ms
Offset Stability ⁽⁷⁾	_		±0.5	_	%V _{FSS}

^{1. 1.0} kPa (kiloPascal) equals 0.145 psi.

- 4. Offset (V_{OFF}) is defined as the output voltage at the minimum rated pressure.
- 5. Response Time is defined as the time for the incremental change in the output to go from 10% to 90% of its final value when subjected to a specified step change in pressure.
- 6. Warm-up Time is defined as the time required for the product to meet the specified output voltage after the pressure is stabilized.
- 7. Offset stability is the product's output deviation when subjected to 1000 hours of Pulsed Pressure, Temperature Cycling with Bias Test.

^{2.} Device is ratiometric within this specified excitation range. Operating the device above the specified excitation range may induce additional error due to device self-heating.

Full Scale Span (V_{FSS}) is defined as the algebraic difference between the output voltage at full rated pressure and the output voltage at the minimum rated pressure.

Maximum Ratings

Table 2. Maximum Ratings⁽¹⁾

Rating	Symbol	Value	Unit
Maximum Pressure (P1 > P2)	P _{MAX}	175	kPa
Burst Pressure (P1 > P2)	P _{Burst}	200	kPa
Storage Temperature	T _{STG}	-40 to +125	°C
Operating Temperature	T _A	-40 to +125	°C

^{1.} Exposure beyond the specified limits may cause permanent damage or degradation to the device.

Figure 1 shows a schematic of the internal circuitry on the stand-alone pressure sensor chip.

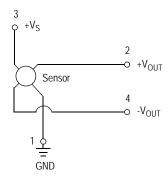


Figure 1. Uncompensated Pressure Sensor Schematic

Voltage Output versus Applied Differential Pressure

The differential voltage output of the sensor is directly proportional to the differential pressure (P1) relative to the vacuum side (P2). Similarly, output voltage increases as

increasing vacuum is applied to the vacuum side (P2) relative to the pressure side (P1).

Temperature Compensation

Figure 2 shows the typical output characteristics of the MPX53 series over temperature.

The piezoresistive pressure sensor element is a semiconductor device which gives an electrical output signal proportional to the pressure applied to the device. This device uses a unique transverse voltage diffused semiconductor strain gauge which is sensitive to stresses produced in a thin silicon diaphragm by the applied pressure.

Because this strain gauge is an integral part of the silicon diaphragm, there are no temperature effects due to differences in the thermal expansion of the strain gauge and the diaphragm, as are often encountered in bonded strain gauge pressure sensors. However, the properties of the strain gauge itself are temperature dependent, requiring that the device be temperature compensated if it is to be used over an extensive temperature range.

Temperature compensation and offset calibration can be achieved rather simply with additional resistive components, or by designing your system using the MPX2053 series sensors.

Several approaches to external temperature compensation over –40 to +125°C and 0 to +80°C are presented in Freescale Application Note, AN840.

LINEARITY

Linearity refers to how well a transducer's output follows the equation: $V_{out} = V_{off} + (sensitivity \times P)$ over the operating pressure range (see Figure 3). There are two basic methods for calculating nonlinearity: (1) end point straight line fit or (2) a least squares best line fit. While a least squares fit gives the "best case" linearity error (lower numerical value), the calculations required are burdensome.

Conversely, an end point fit will give the "worst case" error (often more desirable in error budget calculations) and the calculations are more straightforward for the user. Freescale's specified pressure sensor linearities are based on the end point straight line method measured at the midrange pressure.

Figure 4 illustrates the differential or gauge configuration in the unibody chip carrier (Case 344). A silicone gel isolates the die surface and wire bonds from the environment, while allowing the pressure signal to be transmitted to the silicon diaphragm.

The MPX53 series pressure sensor operating characteristics and internal reliability and qualification tests are based on use of dry air as the pressure media. Media other than dry air may have adverse effects on sensor performance and long term reliability. Refer to application note AN3728, for more information regarding media compatibility.

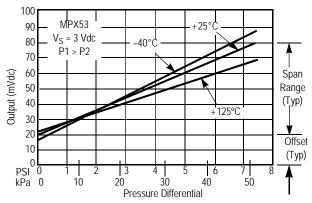


Figure 2. Output vs. Pressure Differential

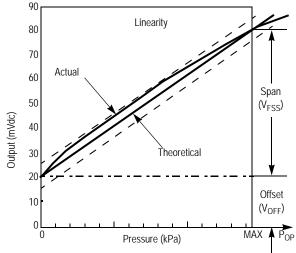


Figure 3. Linearity Specification Comparison

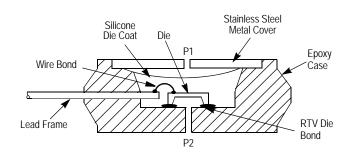


Figure 4. Unibody Package — Cross-Sectional Diagram (Not to Scale)

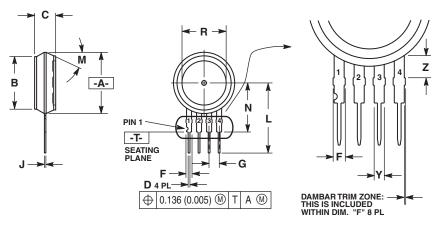
PRESSURE (P1)/VACUUM (P2) SIDE IDENTIFICATION TABLE

Freescale designates the two sides of the pressure sensor as the Pressure (P1) side and the Vacuum (P2) side. The Pressure (P1) side is the side containing silicone gel which isolates the die from the environment. The Freescale MPX pressure sensor is designed to operate with positive differential pressure applied, P1 > P2.

The Pressure (P1) side may be identified by using the following table.

Part Number	Case Type	Pressure (P1) Side Identifier
MPX53D	344	Stainless Steep Cap
MPX53DP	344C	Side with Port Marking
MPX53GP	344B	Side with Port Attached
MPXV53 Series	482C	Side with Port Attached

PACKAGE DIMENSIONS

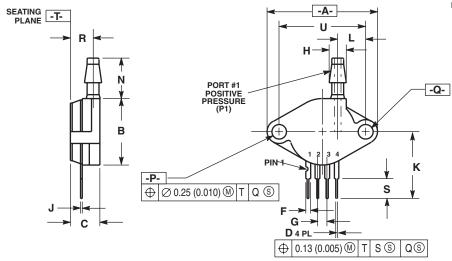


NOTES:

- DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
- 2. CONTROLLING DIMENSION: INCH.
 3. DIMENSION -A- IS INCLUSIVE OF THE MOLD STOP RING. MOLD STOP RING NOT TO EXCEED. 16.00 (0.630).

	INC	HES	MILLIMETERS			
DIM	MIN	MAX	MIN	MAX		
Α	0.595	0.630	15.11	16.00		
В	0.514	0.534	13.06	13.56		
С	0.200	0.220	5.08	5.59		
D	0.016	0.020	0.41	0.51		
F	0.048	0.064	1.22	1.63		
G	0.100	BSC	2.54 BSC			
J	0.014	0.016	0.36 0.40			
L	0.695	0.725	17.65	18.42		
M	30°	NOM	30° NOM			
N	0.475	0.495	12.07	12.57		
R	0.430	0.450	10.92	11.43		
Υ	0.048	0.052	1.22	1.32		
Z	0.106	0.118	2.68	3.00		

CASE 344-15 ISSUE AA UNIBODY PACKAGE

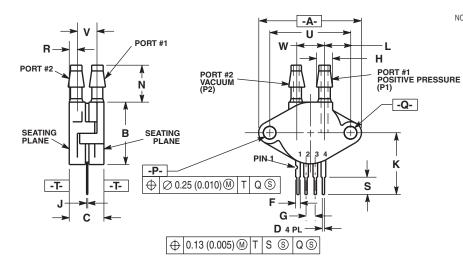


- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- 2. CONTROLLING DIMENSION: INCH.

	INC	HES	MILLIMETERS		
DIM	MIN	MAX	MIN	MAX	
Α	1.145	1.175	29.08	29.85	
В	0.685	0.715	17.40	18.16	
С	0.305	0.325	7.75	8.26	
D	0.016	0.020	0.41	0.51	
F	0.048	0.064	1.22	1.63	
G	0.100 BSC		2.54 BSC		
Н	0.182	0.194	4.62	4.93	
J	0.014	0.016	0.36	0.41	
K	0.695	0.725	17.65	18.42	
L	0.290	0.300	7.37	7.62	
N	0.420	0.440	10.67	11.18	
Р	0.153	0.159	3.89	4.04	
Q	0.153	0.159	3.89	4.04	
R	0.230	0.250	5.84	6.35	
S	0.220	0.240	5.59	6.10	
U	0.910	BSC	23.11	BSC	

CASE 344B-01 ISSUE B UNIBODY PACKAGE

PACKAGE DIMENSIONS

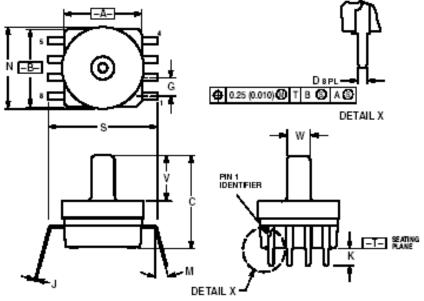


NOTES:

- DIMENSIONING AND TOLERANCING PER ANSI
- 2. CONTROLLING DIMENSION: INCH.

	INCI	HES	MILLIMETERS		
DIM	MIN	MAX	MIN	MAX	
Α	1.145	1.175	29.08	29.85	
В	0.685	0.715	17.40	18.16	
С	0.405	0.435	10.29	11.05	
D	0.016	0.020	0.41	0.51	
F	0.048	0.064	1.22	1.63	
G	0.100	BSC	2.54 BSC		
Н	0.182	0.194	4.62	4.93	
J	0.014	0.016	0.36	0.41	
K	0.695	0.725	17.65	18.42	
L	0.290	0.300	7.37	7.62	
N	0.420	0.440	10.67	11.18	
Р	0.153	0.159	3.89	4.04	
Q	0.153	0.159	3.89	4.04	
R	0.063	0.083	1.60	2.11	
S	0.220	0.240	5.59	6.10	
U	0.910	BSC	23.1	1 BSC	
٧	0.248	0.278	6.30	7.06	
W	0.310	0.330	7.87	8.38	

CASE 344C-01 ISSUE B UNIBODY PACKAGE



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 Y145M, 1982.
- Y143M, 1982.
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 DIMENSON S TO CENTER OF LEAD WHEN
 FORMED PARALLEL.

	NC	HES	MILLIMETERS		
DIN	Ne			NAX	
٨	0.415	0.425	10.54	10.79	
œ	0.415	0.425	1054	10.79	
С	0.500	0.520	12.70	1321	
٥	0.026	0.034	0.66	0.864	
ø	0.100	BSC	254 BSC		
7	0.009	0.011	0.23	0.28	
K	0.100	0.120	254	3.05	
N	0.0	15 ∘	0.0	15 □	
N	0.444	0.448	11.28	11.38	
ø	0.540	0.560	13.72	14.22	
٧	0.245	0.255	622	6.48	
141	0.445	0.400	9.00	0.49	

CASE 482C-03 ISSUE B SMALL OUTLINE PACKAGE

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- Техническая поддержка проекта;
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